

ABSTRACT

A surface acoustic wave device includes a piezoelectric substrate, a comb-shaped electrode formed on a first principal face of the piezoelectric substrate, and a supporting substrate bonded to a second principal face of the piezoelectric substrate. The second principal face of the piezoelectric substrate is bonded to the supporting substrate via a metal layer. A method of manufacturing the surface acoustic wave device includes the steps of: forming a first metal layer on the second principal face of the piezoelectric substrate, forming a second metal layer on a principal face of the supporting substrate, activating the surfaces of the first and second metal layers in plasma atmosphere, bonding the first and second metal layers together at room temperature, and forming the comb-shaped electrode on the first principal face of the piezoelectric substrate.